	<spi< td=""><td>ECIFICAT</td><td>ΓΙΟΝ></td><td></td></spi<>	ECIFICAT	ΓΙΟΝ>			
To:			SPEC.No. ASDI Date: May.	Q-SPE-103(00) 6,2022		
	CUSTOM	ER'S PRODUCT NAM	ME			
	ASDI PRO	DUCT NAME:				
	MVHF160	0808H-SERIES	ļ			
RECEIPT CONFIRM	ATION					
UNCONE	DITIONAL CONSENT		CONDITIONAL CON	NSENT		
	APPROVED		CHECKED			
ASDI SIGNATURE						
AGDI GIGINATURE	APPROVED	CHECKED	PREPARED			
	Xianglong Li	Liang Wang	Jiayin Cai			



REV.	DATE	DESCRIPTION	APPROVED	CHECKED	PREPARED
00	May.21,2022	Initial issue	Xianglong Li	Liang Wang	Jiayin Cai

CAUTION WHEN HANDLING

Before use the products, please read this specification.

CAUTION FOR SAFETY USING

When use the products, be careful to mentioned below for safety using.

CAUTION

*The product should be used within 12 monthes.

Focus on the storage conditions.

Solderability may become weak if it exceeds the period.

*Do not use and store the product in condition of gas corrosion

(Salt, Acid, Alkaline).

*The products must be preheated before soldering.

The operating temperature including self-generated heat must be within '-40°C ~+85°C

*Rework by soldering iron; Please keep the mentioned conditions in this specification.

*In case of insert P.C. Board on chassis, do not add mechanical stress to the product.

*Be careful to arrange of non-magnetic field type inductors.

The error may be caused by magnetic field coupling.

*In case handle the products, please use wrist strap for ground static discharge on human body.

The product keeps away from magnet or magnetized things.

*Do not use the product beyond the mentioned conditions in this specification.

*About an application

The products listed on this specification sheet are intended for use in general electronic equipment (AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition.

*The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet

1)Aerospace/Aviation equipment
2)Military equipment
3)Seabed equipment
4)Safety equipment
5)Medical equipment
2)Transportation control equipment
7)Power-generation control equipment
which directly endanger human life
8)Atomic energy-related equipment
9)Other applications that are not
considered general-purpose applications

If you intend to use the products in the following applications, please contact our sales office. Transportation equipment (cars, electric trains, ships, etc.), Public information-processing equipment, Electric heating apparatus / burning equipment, Disaster prevention/crime prevention equipment When using this product in general-purpose applications, you are kindly requested to take into consideration securing protection circuit/equipment or providing backup circuits, etc., to ensure higher safety.

Xiamen ASDI Electronics Co.,Ltd.

DWG.No. ASDIQ-SPE-103(00)

ISSUE

CUSTOMER	ASDI PART No.	CUSTOMER'S DWG NO.
	MVHF160808H-SERIES	

1.INDEX

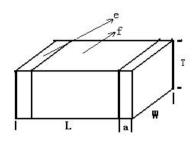
Listed item	Attachment&Tables	Page
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2.Product Spec. Model	Please see (2)	3/9
3.Electrical Characteristics List	Please see (3)	4/9
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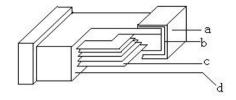
2.Manufacturing Location

China

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(1)Dimension & Inner-configuration





а	Ni/Sn plating	
р	Ag layer	
O	Inner electrode	
d	Body	
е	Terminal electrode	
f	ferrite or ceramic	

No.	Comp	onent	Material		
1	Body		Body		MVHF inductor: ceramic systemAl ₂ O ₃
2	Inner electrode		Ag		
3	Terminal electrode	Ag layer	Ag		
	Terminal electrode	Ni/Sn plating	Ni layer-Sn layer		

Size	L	W	Т	а
160808	1.6±0.20	0.8±0.20	0.8±0.20	0.3±0.2
	(0.063±0.008)	(0.031±0.008)	(0.031±0.008)	(0.012±0.008)

(2)Product Spec. Model

MVHF 160808 H 1N0 S T A B C D E F

A: Product type: MVHF

B: Dimensions: $(L\times W\times T)$ ($(1.6\times 0.8\times 0.8 mm)$

C: Material code:

 D: Inductance
 1N0=1.0nH

 E: Tolerance
 \$ (±0.3nH)

 F:Packaging
 Tape & Reel: T

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(3)Electrical Characteristics List

ASDI Part Number	Customer P/N	Inductance (nH)	Q Value (min)	RDC (Ω)max	Test frequency (MHz)	Test voltage (mV)	SRF (MHz) min	Rated current (mA)max
MVHF160808H1N0 □T		1.00	8	0.05	100	50	10000	500
MVHF160808H1N2 □T		1.20	8	0.05	100	50	10000	500
MVHF160808H1N5 □T		1.50	8	0.10	100	50	6000	500
MVHF160808H1N8 □T		1.80	8	0.10	100	50	6000	500
MVHF160808H2N0 □T		2.00	8	0.10	100	50	6000	500
MVHF160808H2N2 □T		2.20	8	0.10	100	50	6000	500
MVHF160808H2N4 □T		2.40	8	0.12	100	50	6000	500
MVHF160808H2N7 □T		2.70	10	0.12	100	50	6000	500
MVHF160808H3N3 □T		3.30	10	0.15	100	50	6000	500
MVHF160808H3N6 □T		3.60	10	0.16	100	50	6000	500
MVHF160808H3N9 □T		3.90	10	0.16	100	50	6000	500
MVHF160808H4N3 □T		4.30	10	0.18	100	50	6000	500
MVHF160808H4N7 □T		4.70	10	0.20	100	50	6000	500
MVHF160808H5N1 □T		5.10	10	0.25	100	50	5500	500
MVHF160808H5N6 □T		5.60	10	0.25	100	50	5000	500
MVHF160808H6N8 □T		6.80	10	0.30	100	50	5000	500
MVHF160808H7N5 □T		7.50	10	0.35	100	50	4500	500
MVHF160808H8N2 □T		8.20	10	0.35	100	50	4500	500
MVHF160808H9N1 □T		9.10	10	0.40	100	50	3500	500
MVHF160808H10N □T		10.00	12	0.40	100	50	3500	300
MVHF160808H12N □T		12.00	12	0.45	100	50	3000	300
MVHF160808H15N □T		15.00	12	0.50	100	50	2300	300
MVHF160808H18N □T		18.00	12	0.55	100	50	2200	300
MVHF160808H22N □T		22.00	12	0.60	100	50	2000	300
MVHF160808H24N □T		24.0	12	0.60	100	50	2000	300
MVHF160808H27N □T		27.0	12	0.65	100	50	1700	300
MVHF160808H33N □T		33.0	12	0.70	100	50	1500	300
MVHF160808H36N □T		36.0	12	0.70	100	50	1400	300
MVHF160808H39N □T		39.0	12	0.70	100	50	1400	300
MVHF160808H47N □T		47.0	12	0.70	100	50	1200	300
MVHF160808H56N □T		56.0	12	0.75	100	50	1100	300
MVHF160808H68N □T		68.0	12	0.85	100	50	900	300
MVHF160808H82N □T		82.0	8	1.00	100	50	800	300
MVHF160808HR10 □T		100.0	8	1.20	100	50	700	300
MVHF160808HR12 □T		120.0	8	1.40	50	50	600	200
MVHF160808HR15 □T		150.0	8	1.60	50	50	500	200
MVHF160808HR18 □T		180.0	8	1.90	50	50	400	200
MVHF160808HR22 □T		220.0	8	2.40	50	50	350	200
MVHF160808HR27 □T		270.0	8	2.60	50	50	350	150
MVHF160808HR33 □T		330.0	8	2.80	50	50	350	150
MVHF160808HR39 □T		390.0	8	3.20	50	50	300	150
MVHF160808HR43 □T		430.0	8	3.40	50	50	280	150
MVHF160808HR47 □T		470.0	8	3.60	50	50	250	150

□Represents inductance tolerance: Ls<6.8nH, □Please select"B/C/S"level, Ls≥6.8nH, □Please select "H/J"level; B $(\pm 0.1$ nH), C $(\pm 0.2$ nH), S $(\pm 0.3$ nH), H $(\pm 3\%)$, J $(\pm 5\%)$ level.

Explain:
MVHF160808Hseries products have no compensation value, that is, the product test center value is equal to the nominal value of the product.

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(4)Reliability Testing Items

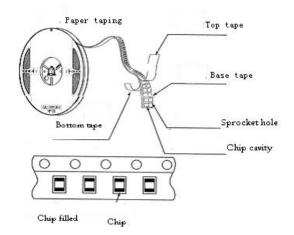
No.	Items	Requirements	Test Methods and Remarks
1	Operating Temperature Range	-40℃~+85℃	
2	Solder ability	At least 95% of terminal electrode should be covered with solder	Preheating temperature:120 $^{\circ}$ C to 150 $^{\circ}$ C Preheating time: 60s Solder 96.5%Sn/3.0%Ag/0.5%Cu of the Sn solder. Solder temperature: 245±5 $^{\circ}$ C Immersion tin depth:10mm Duration: 5±1s Dip performance to a flux of about:3 $^{\sim}$ 5 s
3	Resistance to Soldering	At least 95% of terminal electrode should be covered with solder. No mechanical damage. Inductance : H : change within ±10% Q value change(ceramic): within ±20%	Preheating temperature: 120°C to 150°C Preheating time: 60s Solder 96.5%Sn/3.0%Ag/0.5%Cu of the Sn solder. Solder temperature: 260°C±5°C Immersion tin depth:10mm Duration: 10±1s Dip performance to a flux of about:3 ~ 5 s
4	Adhesion of electrode	The termination and body should be no damage.	Applied force: 7N force for 1608 series. Keep time: 10±1S Chip Glass Epoxy Board Mounting Pad
5	Low temperature resistance	No mechanical damage. Inductance change: within ±10% Q value change(ceramic): within ±20%	Temperature: -40±2°C +24 Testing time: 1000°h
6	Bending strength	No mechanical damage	Testing board: glass epoxy-resin substrate For 0.5 mm/s compression speed, curvature: 2mm, hold time 20s±1s PRE: 1.6mm±0.20mm 读者 0.8mm±0.10mm 85 PRE: 1.45mm±2mm 96mm 98mm 98mm 98mm 98mm 98mm 98mm 98
7	Vibration	No mechanical damage. Inductance change: within ±10% Q value change(ceramic): within ±20%	Amplitude modulation: 1.5mm Test time: A period of 2h in each of 3 mutually perpendicular directions. Frequency range: 10Hz to 55Hz to 10Hz for 1min.
8	High temperature resistance	No mechanical damage. Inductance change: within ±10% Q value change(ceramic): within ±20%	Testing time: 1000.gh Temperature: 85±2°C
9	Static Humidity	No mechanical damage. Inductance change: within ±10% Q value change(ceramic): within ±20%	Humidity: 90% to 95% RH Temperature: $60^{\circ}\pm2^{\circ}$ C +24 Testing time: 1000_{\circ} h
10	High temperature load	No mechanical damage. Inductance change: within ±10% Q value change(ceramic): within ±20%	impose current: at room +24 Testing time: 1000 ₋₀ h Temperature: 85±2°C
11	Temperature Shock	No mechanical damage. Inductance change: within ±10% Q value change(ceramic): within ±20%	Temperature: -55°C for 30±3min +125°C for 30±3min Number of cycles: 100 +125°C 30 min. Ambient 30 min. (max.)

Note: When there are questions concerning, measurement shall be made after 24±2hrs of recovery under the standard condition.

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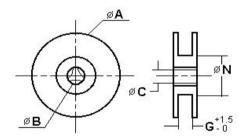
(5)Packaging

5-1, Taping drawings

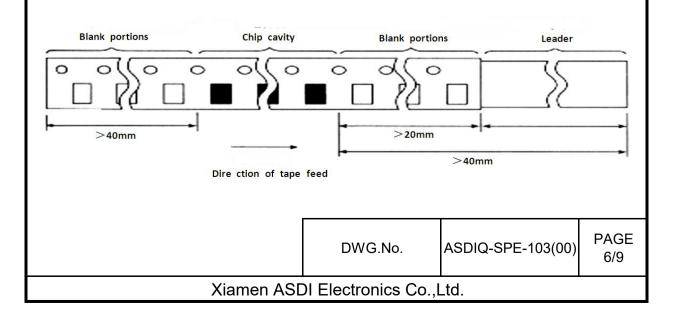


5-2, Reel dimensions (Unit: mm)

Size	Α	В	С	Ν	G
CF-8	178±2.0	22.0±2.0	12.5±1.5	57±2.0	8

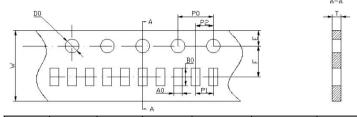


5-3, Leader and blank portion



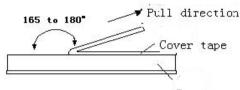
5-4, Taping dimensions (Unit: mm)

Paper tape



Size	A0	В0	W	F	Е	P1	P2	P0	D0	T
160808	1.10±0.2	1.90±0.2	8.0±0.2	3.5±0.1	1.75±0.2	4.0±0.2	2.0±0.1	4.0±0.2	1.55±0.1	0.95±0.1

5-5, Peeling off force



Paper tape

- ①Peeling force should be 0.1~0.7N pulling in the direction of arrow.
- ②Speed of peeling off: 300mm/min.

 ③The cover bond should not be damaged and bond the tape when it peeled off.

5-6,Packaging number (Unit: Pcs)

Size	160808
REEL	4000
BOX	40000
CASE	240000

5-7,Label stick station



(6)Recommend Soldering Conditions

6-1, Soldering Conditions

Products can be applied to reflow soldering.

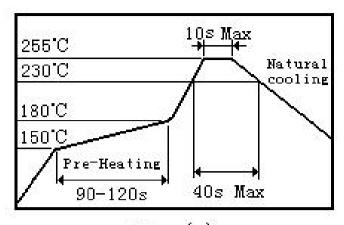
①Soldering conditions

·Pre-heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150°C max. Also cooling into solvent after soldering should be in such way that the temperature difference is limited to 100°C max. Un-enough pre-heating may cause cracks on the ferrite, resulting in the deterioration of product quality.

 $\cdot \text{Products should be soldered within the following allowable range indicated by the slanted line.} \\$ The excessive soldering conditions may cause the corrosion of the electrode. When soldering is repeated, allowable time is the accumulated time.

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6-2, Reflow soldering profile

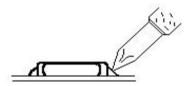


Time(s)

6-3, Iron soldering

Perform soldering at 350°C on 30W max.

Soldering Time: < 5S (Take care not to apply the tip of the soldering iron to the terminal electrodes)



(7)Cleaning

7-1, Cleaning Conditions

Ultrasonic output power: 200W max

(8)Storage Requirements

8-1, Storage period

Products which inspected inductor company over 1 year ago should be examined and used, which can be confirmed with inspection No. marked on the container. Solder ability should be checked if this period is exceeded.

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Xiamen

8-2, Storage conditions

(1)Products should be storage in the warehouse on the following conditions:

Temperature : -10~+40℃ Humidity: 30~70% relative humidity

- (2)Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, oxidization of Electrodes resulting in poor solder ability.
- (3)Products should be storaged on the palette for the prevention of the influence from humidity, dust and so on.
- (4)Products should be storaged in the warehouse without heat shock, vibration, direct sunlight and so on.
- (5)Products should be storaged under the airtight packaged condition.

(9)Usage Of ODS

For ODS listed below, we don't use in process. ODS: CCI4, HCFC, etc.

(10)Notes

- (1) If the parcel label on product is "Unitary lead free" that indicate the products in accord with ROHS appointed requests.
- (2) This product specification guarantees the quality of our product as a single unit, Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
- (3) We can't warrant against failure caused by any use of our product that deviates from the intended use as described in this product specification.

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Xiamen ASDI Electronics Co.,Ltd.

单击下面可查看定价,库存,交付和生命周期等信息

>>ASDI